

57. (New)The assembly recited in claim 55 wherein the solder material has a liquidus temperature of 150 degrees Centigrade or less.

58. (New)The assembly recited in claim 55 wherein the solder material has a liquidus temperature of 140 degrees Centigrade or less.

59. (New)The assembly recited in claim 55 wherein the solder material has a liquidus temperature in the range of 138 to 157 degrees Centigrade.

REMARKS

Claims 1, 6-8, 15-17, and 21 have been amended for clarity. Claims 24-30, which the Examiner restricted to Groups II and III, have been canceled without prejudice. New claims 31-59 have been added to provide Applicants with additional protection to which they are entitled. As a result of this Preliminary Amendment, claims 1-23 and 31-59 are pending in this Application.

The amendments to the claims, and the newly submitted claims, are fully supported by the specification as originally filed, and no new matter has been added. For example, support for the "adhesion layer" recited in each independent claim is described at page 7, lines 20-24. Support for the "solder-wettable layer" recited in each independent claim may be found inter alia at page 8, lines 3-6. Support for the "diffusion layer" may be found at page 7, line 25 through page 8, line 2. Support for the liquidus temperature of the "solderable thermally conductive element" may be found in Table 1 on page 9.

The amendments are made to clarify the claims and are not intended to limit the scope of

RESPONSE TO RESTRICTION REQUIREMENT AND PRELIMINARY AMENDMENT

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equivalents to which any claim element may be entitled.

The Examiner is invited to contact Applicants' representative, Walter W. Nielsen at 602/298-8920 or the below signed attorney if there are any questions regarding this Preliminary Amendment or if prosecution of this application may be assisted thereby.

Respectfully submitted,

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 28 day of June, 2002.

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